

packaging the discrete semiconductor elements, said packaging step comprising fastening the back of the discrete semiconductor elements on the die bond pads and electrically connecting the electrodes of the discrete semiconductor elements and the wire bond pads,

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contd sealing the plurality of discrete semiconductor elements installed on the insulating sheet with an integral sealing resin by sealing the packaging surface of the insulating sheet with the resin, and

dividing the sealing resin into the discrete semiconductor devices by cutting off the sealing resin around the discrete semiconductor elements.

9. (Amended) A method as claimed in claim 8, wherein

the step of packaging further comprises fastening a back side electrode of the discrete semiconductor device onto the corresponding die bond pad to electrically connect the die bond pad and the back side electrode.

10. (Amended) A method as claimed in claim 8, wherein

the dividing step comprises cutting off the sealing resin around a plurality of discrete semiconductor elements grouped as a single body such that at least one of the discrete semiconductor devices comprises a plurality of the discrete semiconductor elements sealed with the integral resin.

11. (Amended) A method for producing a discrete semiconductor device, comprising the steps of:

packaging a plurality of discrete semiconductor elements, said packaging step comprising fastening the back of the discrete semiconductor elements onto an electrically conductive metal sheet and connecting electrically an electrode of each discrete semiconductor element to a specified position of the metal sheet,

sealing the packaging surface of the metal sheet with an integral sealing resin,
cutting off the metal sheet by cutting therein from the back to turn the metal sheet into
die bond pads and wire bond pads which are arranged at intervals, and
dividing the discrete semiconductor devices by cutting off the sealing resin around the
discrete semiconductor elements.

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12. (Amended) A method as claimed in claim 11, wherein
the packaging step comprises fastening the back electrode of the discrete
semiconductor elements onto the metal sheet and electrically connecting the metal sheet and
the back electrode.

13. (Amended) A method as claimed in claim 11, wherein
the dividing step comprises cutting off the sealing resin around a plurality of discrete
semiconductor elements grouped as a single body, to divide the discrete semiconductor
devices each carrying the plurality of discrete semiconductor elements being sealed with the
integral resin.

14. (Amended) A method as claimed in claim 11, wherein
the step of cutting off the metal sheet comprises cutting off the metal sheet such that
the die bond pads and/or the wire bond pads connected to the plurality of discrete
semiconductor elements become an integral body, and
the dividing step comprises cutting off the sealing resin around the discrete
semiconductor elements which are formed so that the die bond pads and/or the wire bond
pads connected to the plurality of discrete semiconductor elements become an integral body,
thereby to obtain the discrete semiconductor device wherein the plurality of discrete
semiconductor elements which share the die bond pads and/or the wire bond pads in common
are sealed with the integral resin.